

RELIABILITY REPORT  
FOR  
MAX7221CWG+  
PLASTIC ENCAPSULATED DEVICES

February 22, 2011

**MAXIM INTEGRATED PRODUCTS**

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## Conclusion

The MAX7221CWG+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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### I. Device Description

#### A. General

The MAX7219/MAX7221 are compact, serial input/output common-cathode display drivers that interface microprocessors ( $\mu$ Ps) to 7-segment numeric LED displays of up to 8 digits, bar-graph displays, or 64 individual LEDs. Included on-chip are a BCD code-B decoder, multiplex scan circuitry, segment and digit drivers, and an 8x8 static RAM that stores each digit. Only one external resistor is required to set the segment current for all LEDs. The MAX7221 is compatible with SPI(tm), QSPI(tm), and MICROWIRE(tm), and has slew-rate-limited segment drivers to reduce EMI. A convenient 4-wire serial interface connects to all common  $\mu$ Ps. Individual digits may be addressed and updated without rewriting the entire display. The MAX7219/MAX7221 also allow the user to select code-B decoding or no-decode for each digit. The devices include a 150 $\mu$ A low-power shutdown mode, analog and digital brightness control, a scan-limit register that allows the user to display from 1 to 8 digits, and a test mode that forces all LEDs on. For applications requiring 3V operation or segment blinking, refer to the MAX6951 data sheet.

## II. Manufacturing Information

A. Description/Function:	Serially Interfaced, 8-Digit, LED Display Drivers
B. Process:	S12
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Philippines
F. Date of Initial Production:	July 26, 1997

## III. Packaging Information

A. Package Type:	24-pin SOIC (W)
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-0501-0140
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	85°C/W
K. Single Layer Theta Jc:	18°C/W
L. Multi Layer Theta Ja:	N/A
M. Multi Layer Theta Jc:	N/A

## IV. Die Information

A. Dimensions:	80 X 93 mils
B. Passivation:	Si <sub>3</sub> N <sub>4</sub> /SiO <sub>2</sub> (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	1.2 microns (as drawn)
F. Minimum Metal Spacing:	1.2 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO <sub>2</sub>
I. Die Separation Method:	Wafer Saw

**V. Quality Assurance Information**

- A. Quality Assurance Contacts: Don Lipps (Manager, Reliability Engineering)  
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.  
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

**VI. Reliability Evaluation**

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 80 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 13.7 \times 10^{-9}$$

$$\lambda = 13.7 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the S12 Process results in a FIT Rate of 0.17 @ 25C and 3.00 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (lot BH8AAQ001D D/C 9722)

The DD10 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1000V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

**Table 1**  
Reliability Evaluation Test Results

**MAX7221CWG+**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
<b>Static Life Test</b> (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	80	0	BH8BAQ001B, D/C 9712

Note 1: Life Test Data may represent plastic DIP qualification lots.